SLOVENSKI STANDARD
kSIST FprEN 16602-70-38:2018

01-september-2018

Zagotavljanje kakovosti proizvodov v vesoljski tehniki - Visoka zanesljivost spajkanja za površinsko montažo in mešano tehnologijo

Space product assurance - High-reliability soldering for surface-mount and mixed technology

Raumfahrtproduktsicherung - Hochzuverlässiges Löten von Oberflächen-Befestigungen und gemischte Technologien

Assurance produit spatiale - Soudure haute fiabilité pour technologies à montage de surface et mixte

Ta slovenski standard je istoveten z: **FprEN 16602-70-38**

ICS:

25.160.50	Trdo in mehko lotanje	Brazing and soldering
49.140	Vesoljski sistemi in operacije	Space systems and operations

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EUROPEAN STANDARD

NORME EUROPÉENNE

EUROPÄISCHE NORM

FINAL DRAFT
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ICS 25.160.50; 49.140

English version

Space product assurance - High-reliability soldering for surface-mount and mixed technology

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If this draft becomes a European Standard, CEN and CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

This draft European Standard was established by CEN and CENELEC in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CEN and CENELEC member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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Recipients of this draft are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

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Table of contents

Figures

Tables

European Foreword

This document (FprEN 16602-70-38:2018) has been prepared by Technical Committee CEN/CLC/TC 5 “Space”, the secretariat of which is held by DIN (Germany).

This document (FprEN 16602-70-38:2018) originates from ECSS-Q-ST-70-38C Rev.1.

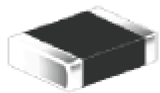
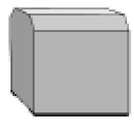
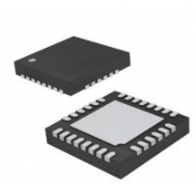
This document is currently submitted to the Unique Acceptance Procedure.

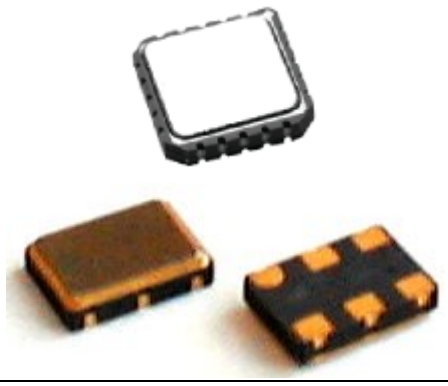
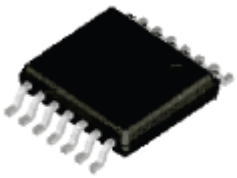
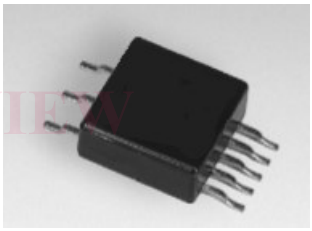
This document has been developed to cover specifically space systems and will the-refore have precedence over any EN covering the same scope but with a wider do-main of applicability (e.g.: aerospace).

This document has been prepared under a mandate given to CEN by the European Commission and the European Free Trade Association.

Introduction

This Standard prescribes requirements for electrical connections of leadless and leaded surface mounted devices (SMD) on spacecraft and associated equipment, utilising a range of substrate assemblies and employing solder as the interconnection media. The principal types of SMDs can be gathered in the following families:

Rectangular and square end-capped or end-metallized device with rectangular body, leadless chip (see 11.5.2) e.g. end capped chip resistors and end capped chip capacitors.	
Cylindrical and square end-capped devices with cylindrical body, leadless chip (see 11.5.4) e.g. MELF for cylindrical end capped or e.g. D-5A for square end capped	 
Bottom terminated chip device (see 11.5.3) This type of device has metallised terminations on the bottom side only. e.g. inductors and SMD0.5, SMD1, SMD2, SMD0.2, SMD0.22 e.g. Quad Flat Pack No lead (QFN)	  

Castellated chip carrier device (see 11.5.5) The main device of this type is leadless ceramic chip carrier (LCCC). e.g. LCC6	
Flat pack and gull-wing leaded device with round, rectangular , ribbon leads (see 11.5.6) e.g. small-outline transistor (SOT), small—outline package (SO), flat pack and quad flat pack (QFP) and SMD connectors with stress-relief. This family also comprises devices for through-hole mounting that have been reconfigured to surface mounting.	
Moulded magnetics (see 11.5.13) e.g. 1553 interface transformers or specific transformers	 
"J" leaded device (see 11.5.7) e.g. ceramic leaded chip carriers (CLCC) and plastic leaded chip carriers (PLCC).